**New silicone gap filler from Wevo: innovative solution for thermal management of electronic components**

**Ostfildern-Kemnat, Germany. With WEVOSIL 26040 FL, Wevo is expanding its portfolio of thermal interface materials (TIMs) with a specially optimised silicone gap filler. The material features high thermal conductivity of 4 W/m\*K, a very low bond line thickness (< 70 µm) and enhanced sedimentation stability. In addition, the dosing profile has been sharpened to secure an efficient production process. So, the new thermally conductive material offers a process- and application-optimised solution for the thermal management of numerous electrical and electronic applications, from power electronics to battery technologies.**

Whether it’s high dosage volumes, reliable heat dissipation for large surfaces or mechanically demanding thermal joints that are needed – the new silicone gap filler from Wevo is a state-of-the-art solution for numerous requirements in contemporary electronics and electrical engineering. With a thermal conductivity of 4 W/m\*K, measured according to ASTM D5470-2017, the product ensures efficient heat dissipation and also bridges small gaps thanks to the specially developed filler combination and the resulting very low bond line thickness of < 70 µm. Furthermore, material properties such as reactivity can be customised to individual needs.

**Thermal interface material with optimised dosing profile**

At the same time, the material has been formulated to be very resistant to sedimentation, allowing it to be stored, used and also transported over long distances over a period of at least three months without having to be rehomogenized. Moreover, the optimised dosing properties permit simple and efficient handling, high dispensing speeds and fine dosing patterns. Compared to thermally conductive pads, this ensures significantly greater precision and flexibility in production, which is particularly advantageous when manufacturing large unit volumes.

In addition, the newly developed silicone gap filler offers high temperature resistance of up to 200 °C, flame-retardant properties in accordance with UL 94 V-0 (as of a thickness of just 2 mm) and good mechanical properties, including elongation at break of more than 30 per cent. When cured, WEVOSIL 26040 FL meets the requirements of the PV 3040 test specification for low-volatile emissions in the automotive industry and is therefore suitable for a wide range of applications.

With its state-of-the-art, customisable properties, Wevo’s new thermally conductive material helps ensure the safe operation and longevity of innovative electronic and electrical components.

**Image description and source**

From battery technologies to power electronics, the new silicone gap filler from Wevo enables efficient thermal management (Image source: WEVO-CHEMIE GmbH).

(Please note that the image may only be used in the context of this press release).

***About Wevo***

*WEVO-CHEMIE GMBH is an international, independent chemicals company headquartered in Germany and with further companies in Asia, China and the USA. Wevo develops and manufactures innovative potting applications as well as special bonding and sealing applications based on polyurethane, epoxy and silicone – primarily for applications in electrical and electronic components. Wevo products protect sensitive components against chemicals, vibration, foreign bodies, dust, moisture and high temperatures.*

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